

Impact of the Al Mole Fraction in the Bulk- and Surface-State Induced Instability of AlGaN/GaN HEMTs

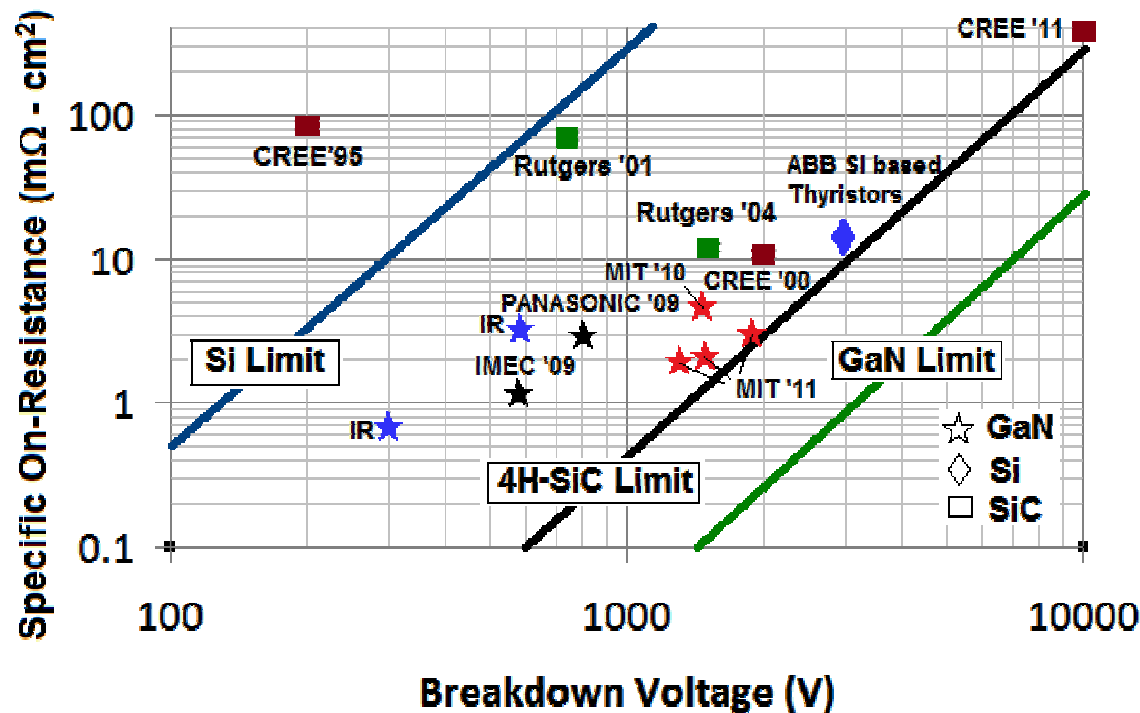
S. DasGupta¹, M. Sun², A. Armstrong¹, R. Kaplar¹, M. Marinella¹, J. Stanley¹, M. Smith¹, S. Atcitty¹ and T. Palacios²

¹Sandia National Laboratories, Albuquerque, NM 87185 USA

² Department of Electrical Engineering and Computer Science,
Massachusetts Institute of Technology, Cambridge, MA 02139 USA.

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GaN HEMTs for High Breakdown Voltage



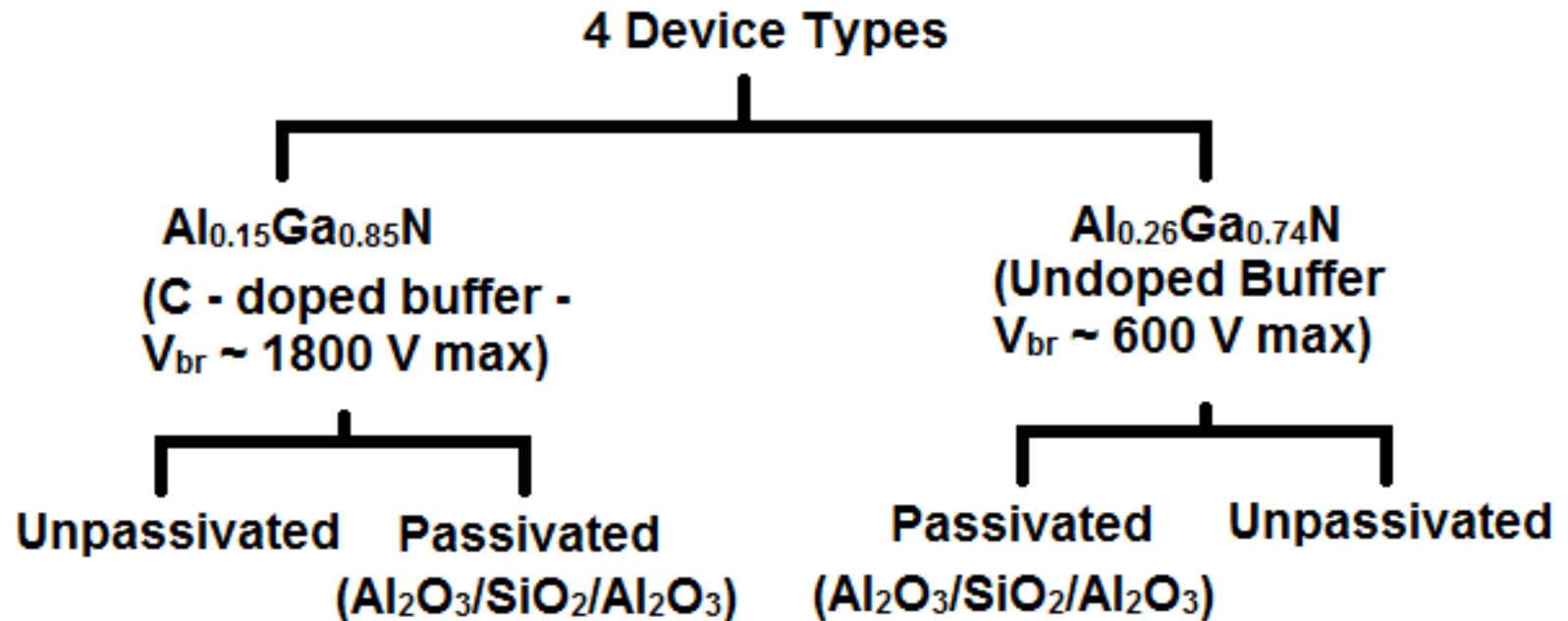
Wide bandgap GaN – theoretically has the highest breakdown voltage limit for given R_{on} (among Si, SiC, GaN)
Greater commercial capability due to integration on Silicon.

Low Al percentage AlGaN required to reduce 2DEG density.
Carbon doping employed in buffer to avoid punch-through.

Degradation mechanisms widely studied for RF HEMTs, with larger Al molefraction.
Low Al molefraction AlGaN has been studied comparatively less.

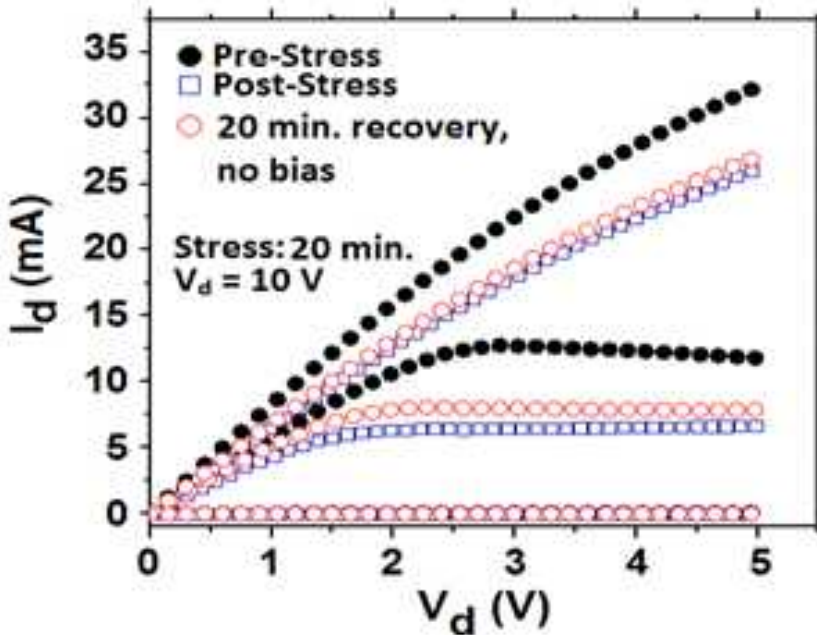


The Devices

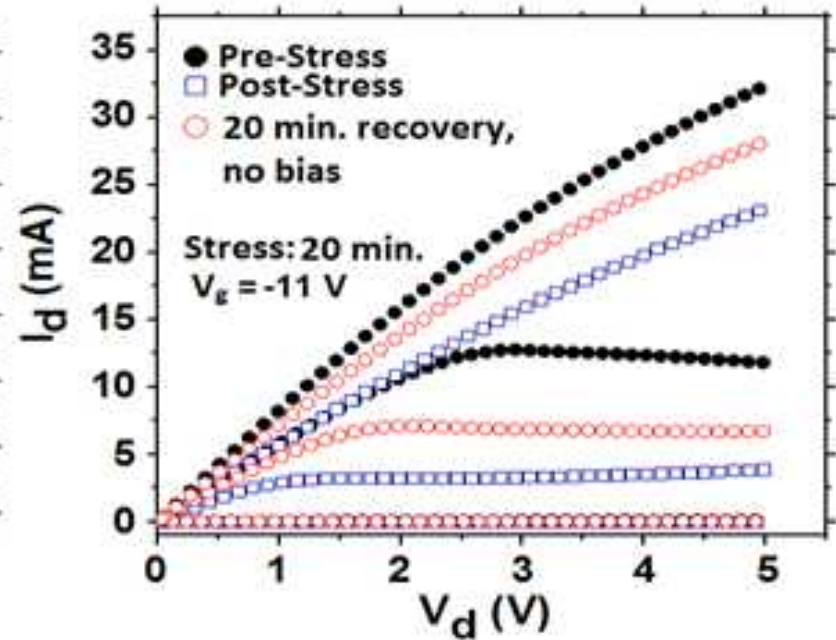


All devices grown on (111) Silicon

Difference Between On-State and Off-State Stress



$$V_{ds} = 10V, V_{gs} = 0V$$

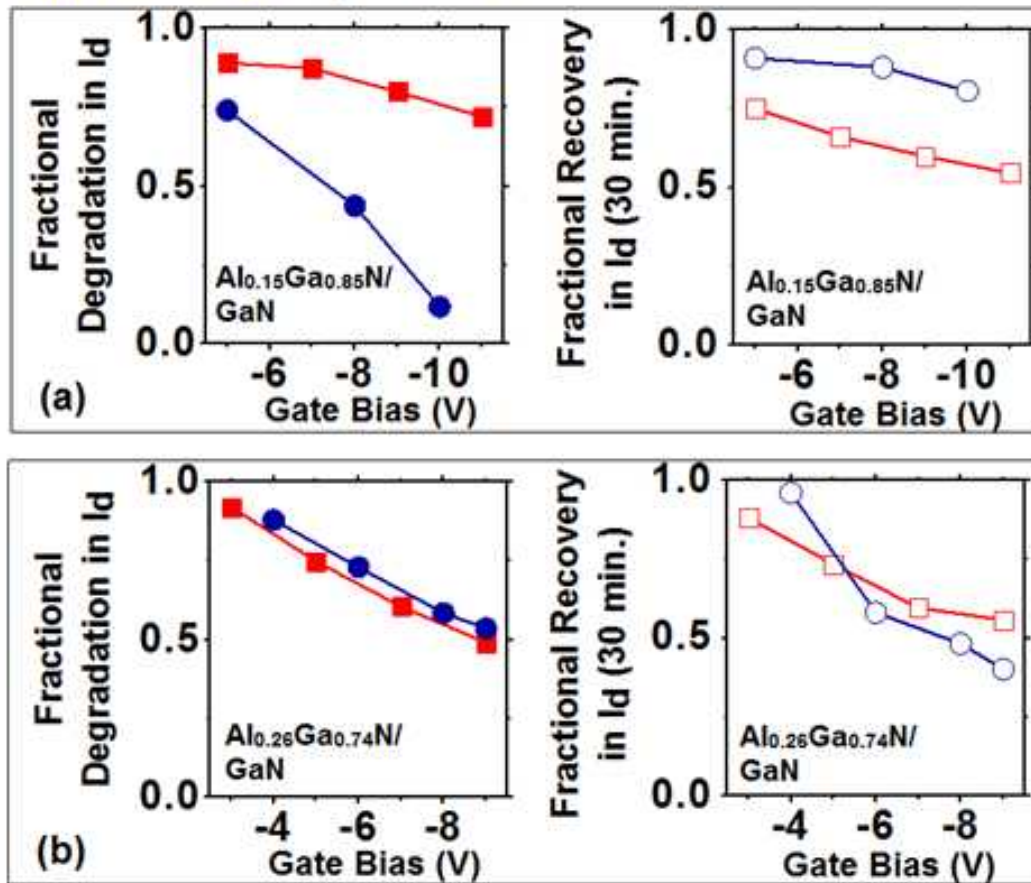


$$V_{ds} = 0V, V_{gs} = -11V$$

On-State drain bias produces much slower recovery than Off-State gate bias.

Passivated vs Unpassivated – $\text{Al}_{0.15}\text{Ga}_{0.85}\text{N}$ vs $\text{Al}_{0.26}\text{Ga}_{0.74}\text{N}$

Passivated ■ Degradation □ Recovery
Unpassivated ● Degradation ○ Recovery



Fractional Recovery

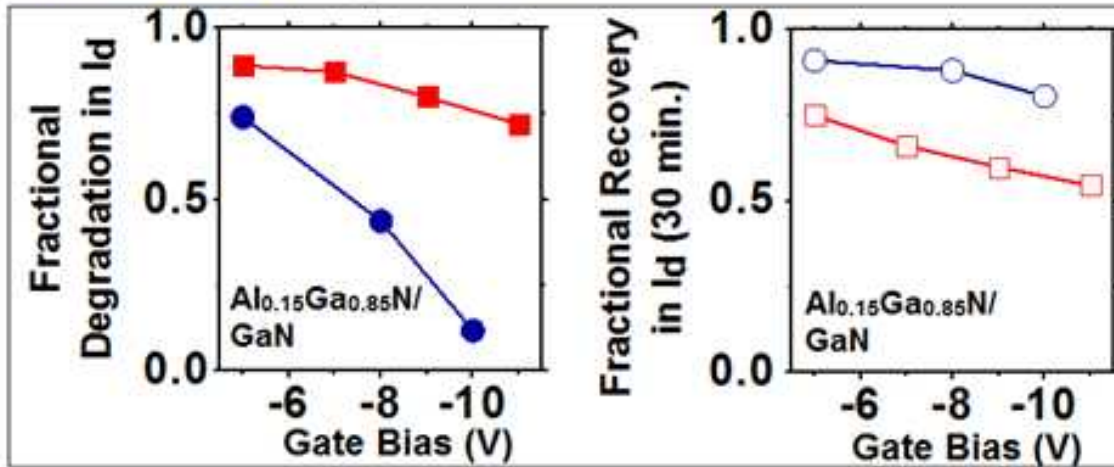
$$= (I_{d,post-recovery} - I_{d,post-stress}) / (I_{d,pre-stress} - I_{d,post-stress})$$
 at $V_{gs} = 1 \text{ V}$, $V_{ds} = 5 \text{ V}$.

Lack of passivation substantially increases trapping with fast recovery in $\text{Al}_{0.15}\text{Ga}_{0.85}\text{N}$ compared to $\text{Al}_{0.26}\text{Ga}_{0.74}\text{N}$

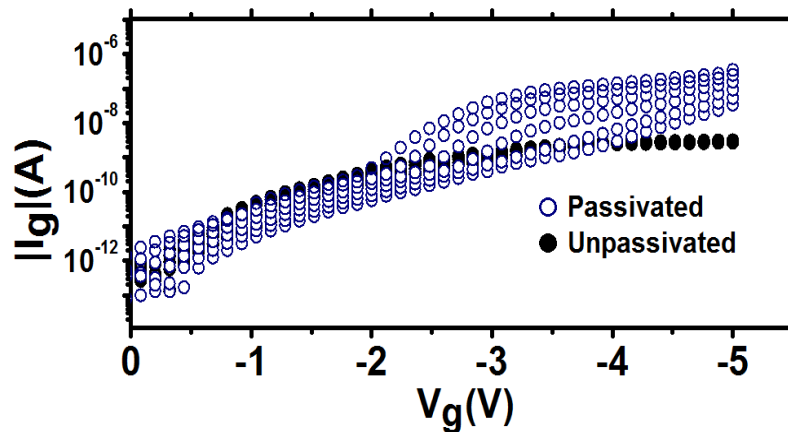
Passivated vs Unpassivated –



Passivated ■ Degradation □ Recovery
Unpassivated ● Degradation ○ Recovery

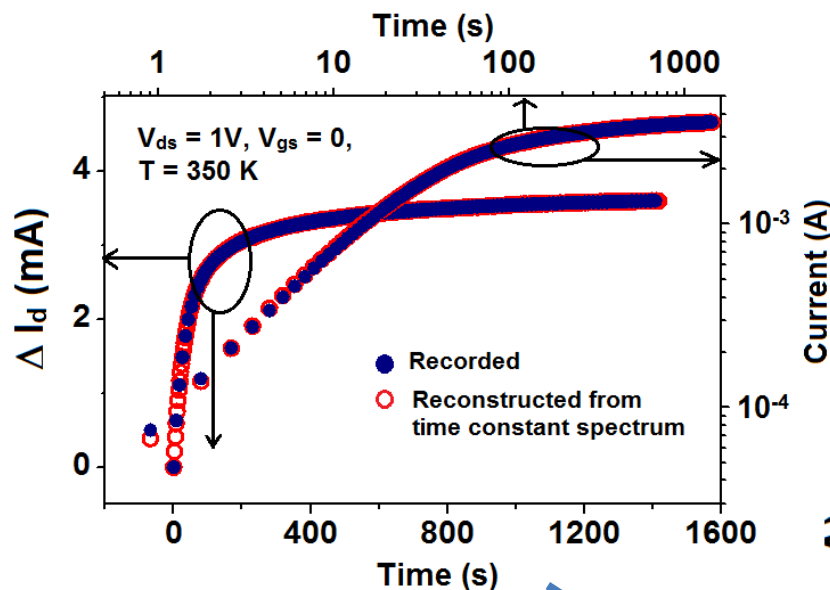


Passivation improves stability greatly, but gate leakage increases.



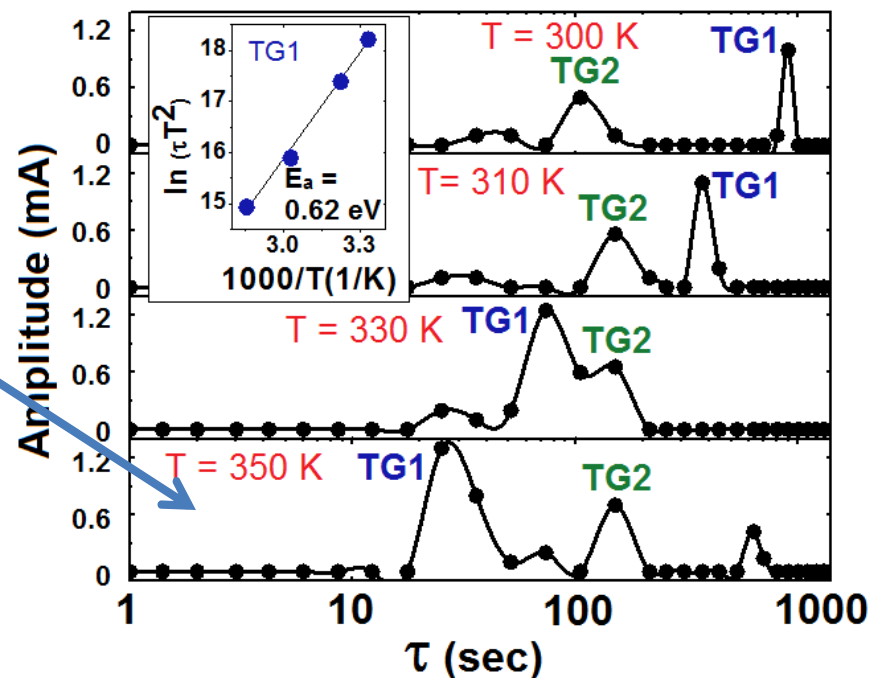
Large width power devices – require low gate leakage per unit length. Better gate dielectric need with $\text{Al}_{0.15}\text{Ga}_{0.85}\text{N}$.

I-t based time constant spectra

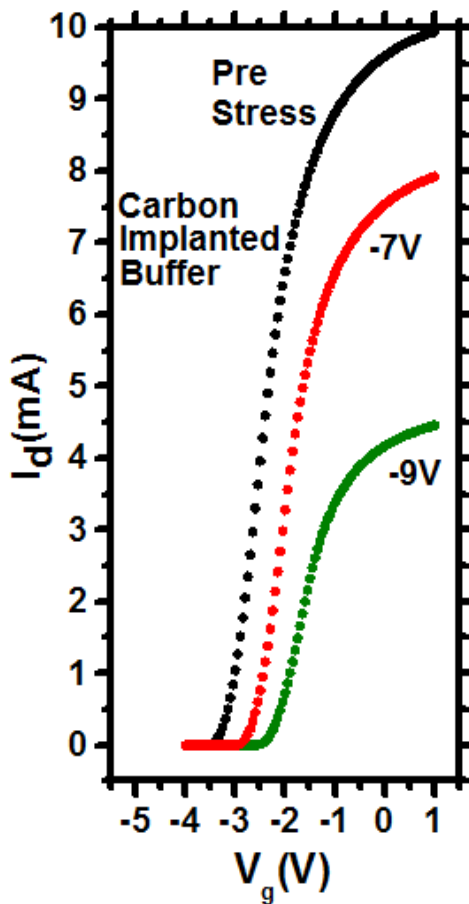
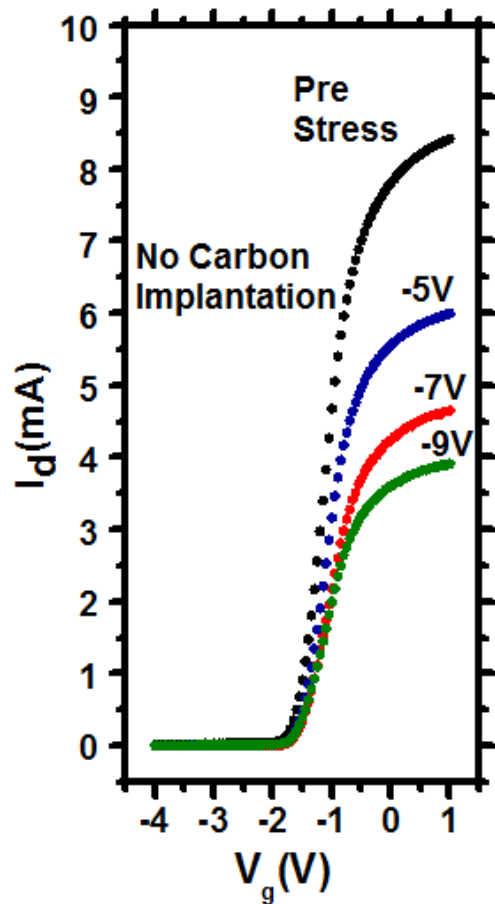


Two peaks – TG1 ($E_a \sim 0.62$ eV) and TG2 are seen

TG1 is temperature independent – most likely due to tunneling into 2DEG states



V_{th} shifts and spatial location of TG1, TG2

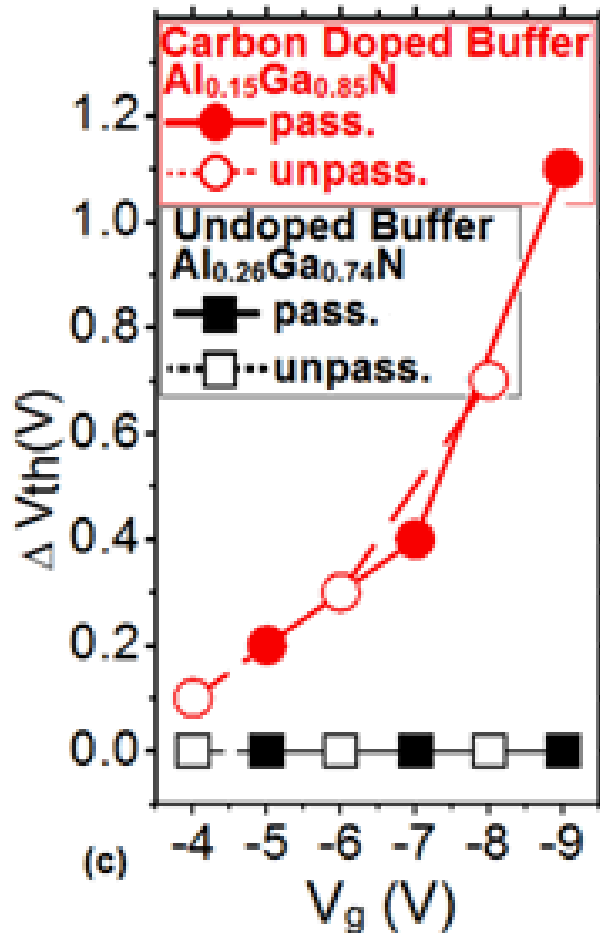


$Al_{0.15}Ga_{0.85}N$ devices (carbon doped) show V_{th} shifts, unlike the $Al_{0.26}Ga_{0.74}N$. Even for more than 50 % current degradation – no V_{th} shift in non-carbon implanted devices.

$AlGaN$ is depleted .
Gate is fairly long (2 microns) – near gate trapping should not induce threshold shifts.

V_{th} shift is most likely due trapping in carbon-doped buffer.

V_{th} shifts and spatial location of TG1, TG2



TG1, TG2 are seen in all devices.

V_{th} shift in carbon doped samples – there are enough buffer carriers in off-state to induce V_{th} shifts.

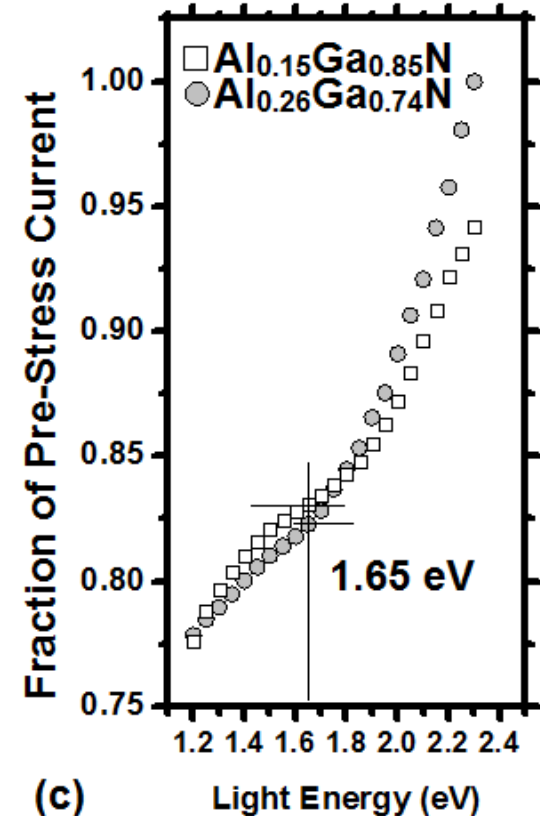
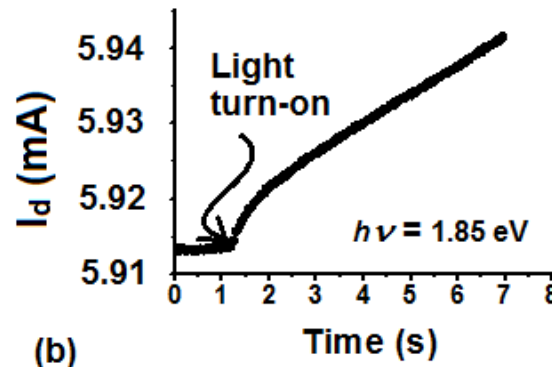
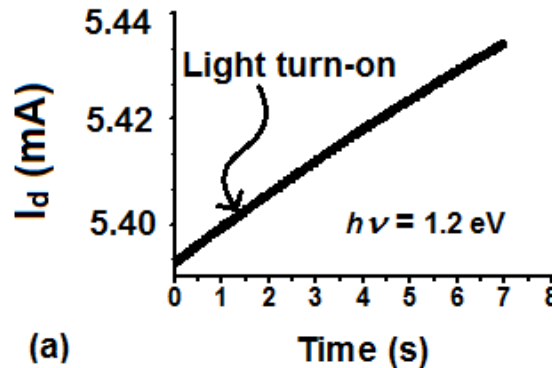
Should have induced slowly recoverable V_{th} shifts in all devices if they were buffer traps

Consistent with being AlGaN traps

On-State Drain Bias and Optical Detrapping

Less than 50 % of the current due to on-state drain bias recovered thermally – so optical detrapping used.

Emission detected at ~ 1.65 eV.





Conclusions

- Gate and Drain Stress produce trapping with different detrapping characteristics
- $\text{Al}_{0.15}\text{Ga}_{0.85}\text{N}$ shows much more vulnerability to gate stress in absence of passivation than $\text{Al}_{0.26}\text{Ga}_{0.74}\text{N}$ in absence of passivation.
- Buffer Carbon doping introduces threshold voltage shifts.
- Two components TG1 ($E_a = 0.62$ eV), TG2 (negligible temperature dependence observed in detrapping).
- Majority of drain bias induced degradation recovered at optical illumination with 1.65 eV and higher.